PLPVQ 940A

BIDOS®

VCSEL pulsed laser in small footprint QFN





Applications

- Flash & Autofocus

Gesture Recognition

Features:

- Multimode VCSEL
- Laser aperture 10 μm (diameter) x 40 μm (pitch)
- Cost effective package for high volume applications

Ordering Information

Type Peak output power Ordering Code

typ.

 $I_{_{\rm F}}$ = 1 A; $t_{_{\rm D}}$ = 9 ms; f = 60 Hz; $T_{_{\rm A}}$ = 25 °C

Pont

PLPVQ 940A 0.6 W Q65112A6002

Maximum Ratings

 $T_A = 25 \,^{\circ}C$

Parameter	Symbol		Values
Operating temperature	T _{op}	min. max.	0 °C
Storage temperature	T_{stg}	min. max.	-40 °C 85 °C
Junction temperature 1)	T _j	max.	110 °C
Output power (continuous wave)	P _{cw}	max.	0.48 W
Forward current	I _F	max.	0.75 A
Pulse current	I _{FSM}	max.	1.2 A
Reverse voltage 2)	V_{R}	max.	5 V



Characteristics

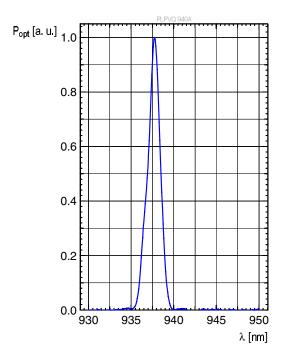
 $I_{_{\rm F}}$ = 1 A; $t_{_{\rm p}}$ = 9 ms; f = 60 Hz; $T_{_{\rm A}}$ = 25 °C

Parameter	Symbol		Values
Peak wavelength	$\lambda_{\sf peak}$	min. typ. max.	932 nm 940 nm 948 nm
Spectral bandwidth at 50% I _{e,rel,max}	Δλ	typ.	1.5 nm
Peak output power	P_{opt}	min. typ. max.	0.5 W 0.6 W 0.75 W
Field of view (HFOV)	Θ	typ.	65 °
Field of view (VFOV)	$\Theta_{_{\perp}}$	typ.	78 °
Wall plug efficiency (after diffusor)	WPE	typ.	27 %
Threshold current	I _{th}	typ.	0.11 A
Forward voltage	$V_{_{\rm F}}$	min. typ. max.	1.5 V 2.2 V 2.5 V
Rise time	t _r	typ.	1 ns
Fall time	t _f	typ.	1 ns
Aperture size (diameter)		typ.	10 µm
Temperature coefficient of wavelength	TC _λ	typ. max.	0.07 nm / K 0.1 nm / K
Thermal resistance junction solder point real	R_{thJS}	max.	22 K / W



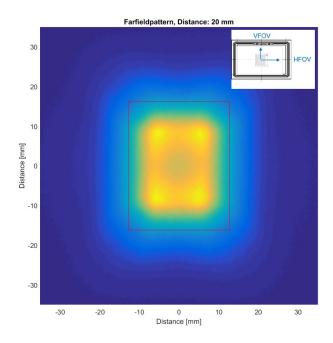
Relative Spectral Emission 3), 4)

$$P_{opt} = f(\lambda); t_p = 9 \text{ ms}$$



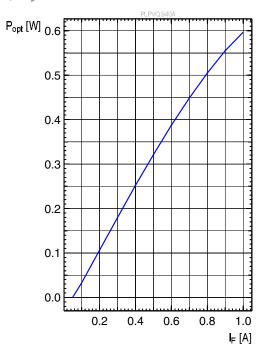
Far-Field Illumination Pattern 3), 4)

 P_{opt} = 0.6 W; d = 20 mm (distance to flat screen)



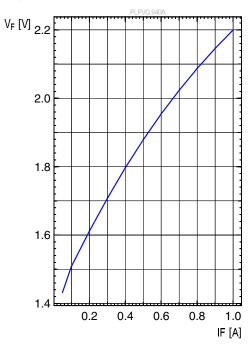
Optical Output Power 3), 4)

$$P_{opt} = f(I_F), t_p = 9 \text{ ms}$$



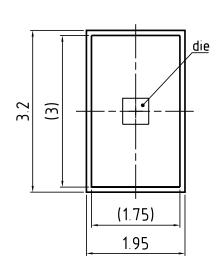
Forward Voltage 3)

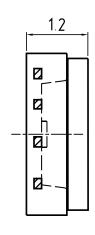
$$V_{F} = f(I_{F}); t_{p} = 9 \text{ ms}$$

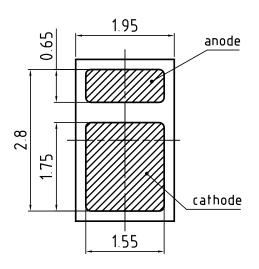


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Dimensional Drawing 5)







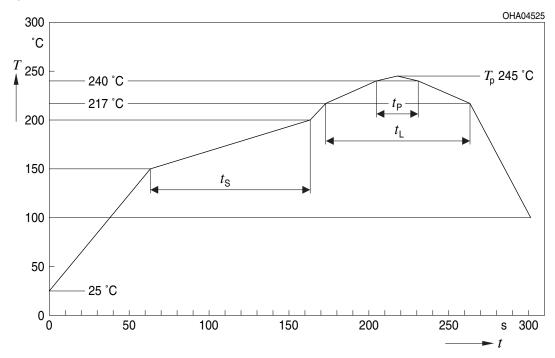
C67062-A0276-A1-03

Approximate Weight: 5.0 mg



Reflow Soldering Profile

Product complies to MSL Level 3 acc. to JEDEC J-STD-020E



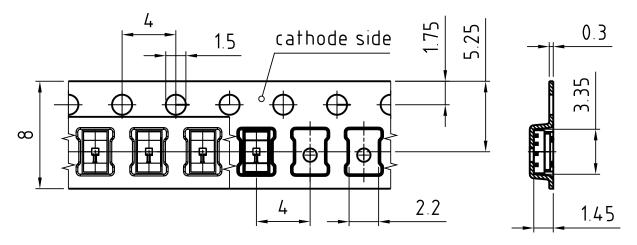
Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*)			2	3	K/s
25 °C to 150 °C					
Time t _s	t _s	60	100	120	S
T_{Smin} to T_{Smax}					
Ramp-up rate to peak*)			2	3	K/s
T_{Smax} to T_{P}					
Liquidus temperature	T_L		217		°C
Time above liquidus temperature	$t_{\scriptscriptstyle \perp}$		80	100	S
Peak temperature	T_{P}		245	260	°C
Time within 5 °C of the specified peak	t _P	10	20	30	S
temperature T _P - 5 K					
Ramp-down rate*			3	6	K/s
T _P to 100 °C					
Time				480	S
25 °C to T _P					

All temperatures refer to the center of the package, measured on the top of the component



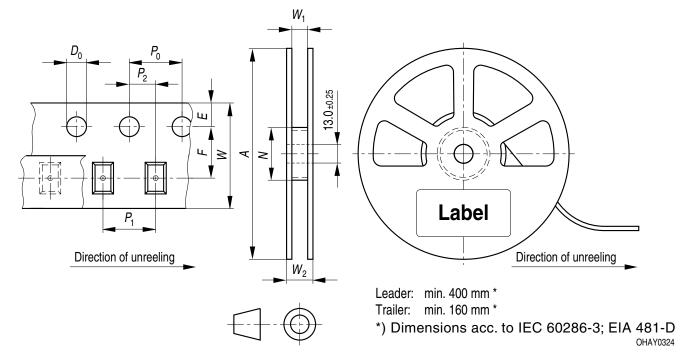
^{*} slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

Taping 5)



C67062-A0276-B6-01

Tape and Reel 6)





180 mm

Reel	dimensions [mm]				
Α	W	N_{\min}	W_1	$W_{2 max}$	Pieces

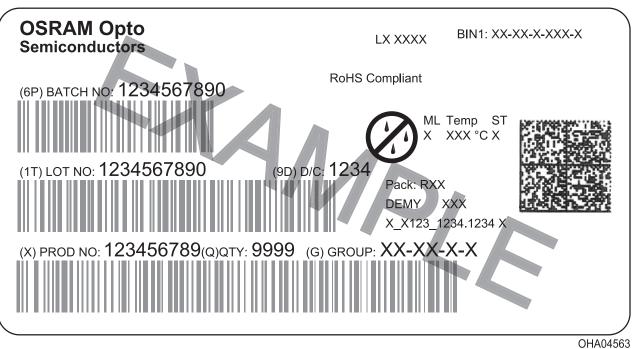
60

8.4 + 2

14.4

8 + 0.3 / - 0.1

Barcode-Product-Label (BPL)

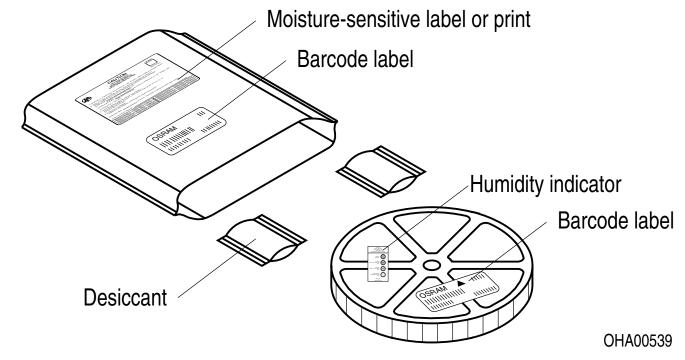




per PU

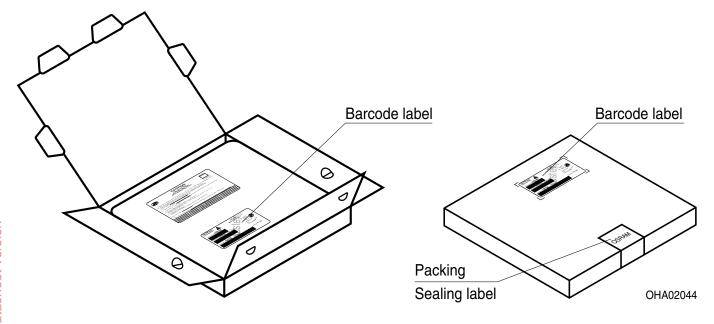
2500

Dry Packing Process and Materials 5)



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.

Schematic transportation box 5)





Dimensions of transportation box in mm			
Width	Length	Height	
200 ± 5 mm	195 ± 5 mm	30 ± 5 mm	



Notes

Depending on the mode of operation, these devices emit highly concentrated visible and non visible light light which can be hazardous to the human eye. Products which incorporate these devices have to follow the safety precautions given in IEC 60825-1.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related informations please visit www.osram-os.com/appnotes



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Glossary

- ¹⁾ **Junction temperature:** Limited due to plastic package, not due to laser chip.
- ²⁾ **Reverse Operation:** Reverse Operation of 10 hours is permissible in total. Continuous reverse operation is not allowed.
- Typical Values: Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- ⁴⁾ **Testing temperature:** TA = 25°C
- Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- ⁶⁾ **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.



Revision History			
Version	Date	Change	
0.1	2018-11-30	Brand	



Preliminary datasheet version

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